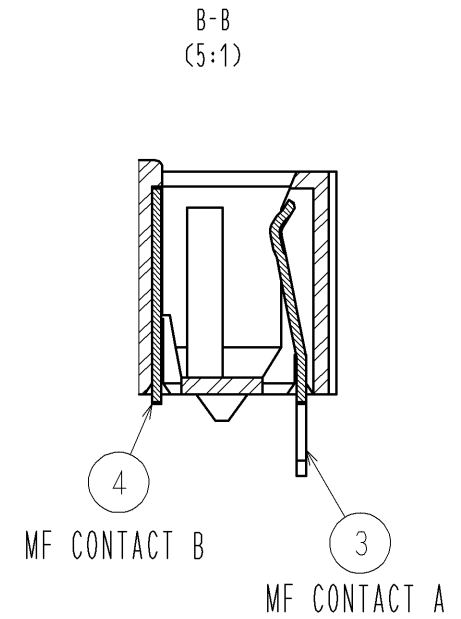
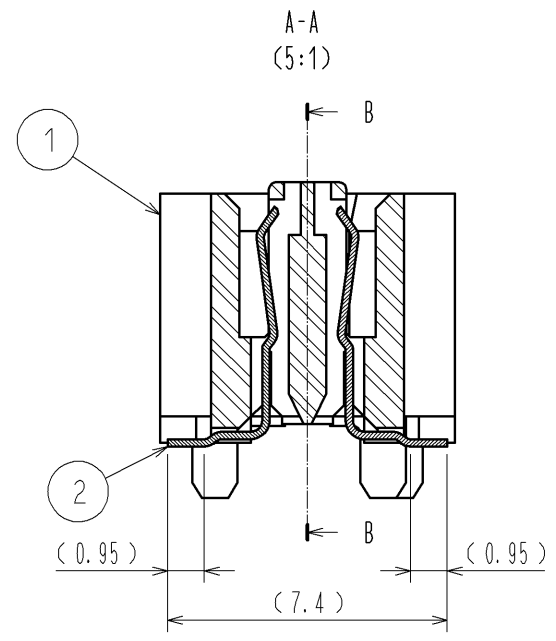
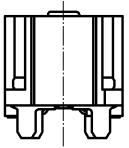
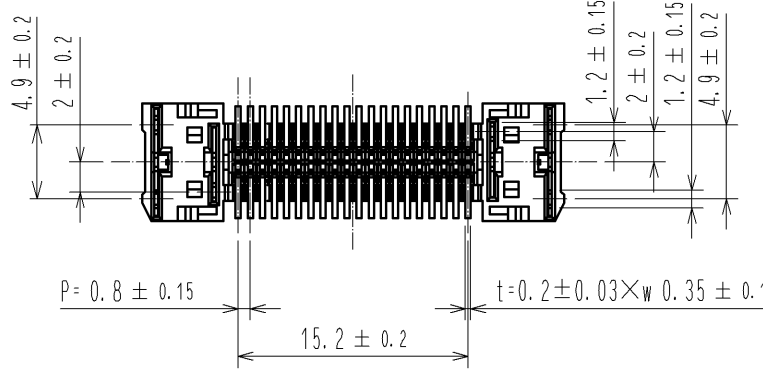
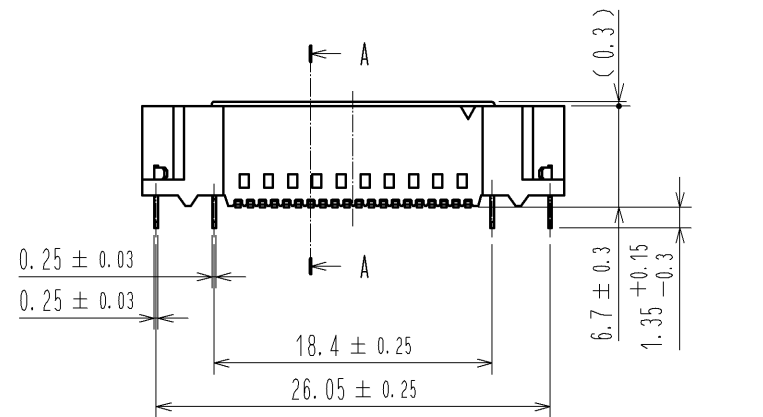
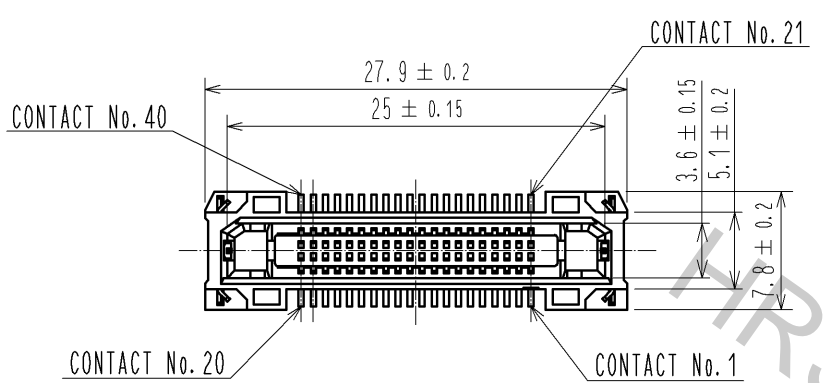
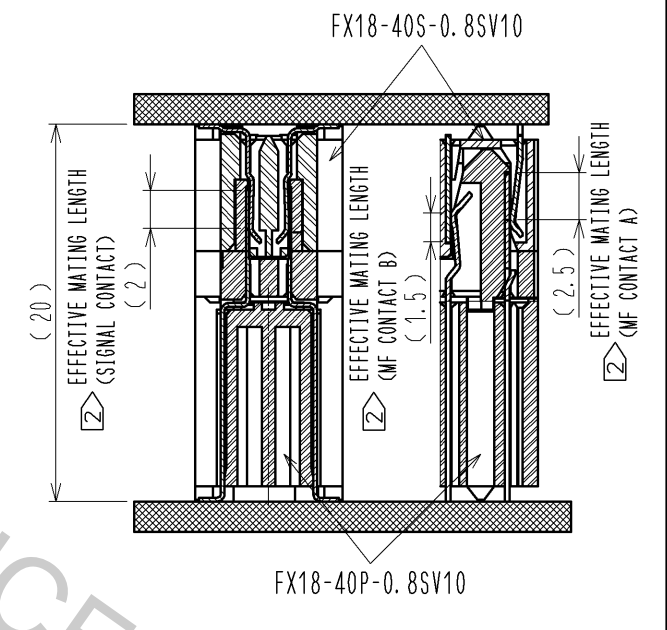
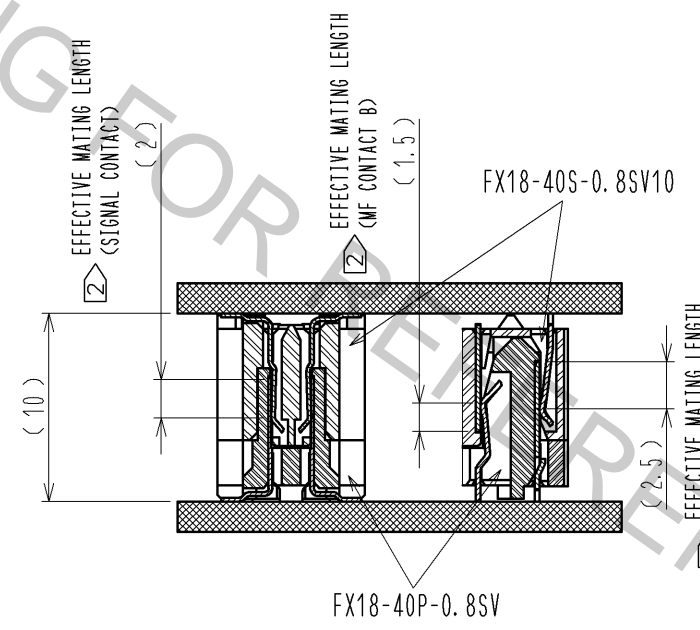


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CROSS SECTION OF MATING(FREE)  
STACKING HEIGHT=10mm

CROSS SECTION OF MATING(FREE)  
STACKING HEIGHT=20mm



- NOTE 1 LEAD CO-PLANARITY IS 0.1mm MAX.  
 2 CONTACTS ARE 3 STEPS SEQUENTIAL. (MF CONTACT A=>SIGNAL CONTACT=>MF CONTACT B) WHEN USING THIS SEQUENTIAL STRUCTURE, PLEASE AVOID ANGLED INSERTION.  
 3 MF CONTACT A AND MF CONTACT B CAN BE USED AS POWER SUPPLY CONTACT. (3A/PIN MAX)  
 4 IT SHOWS THE VACUUM PICKUP AREA. (SEE PAGE 2) REMOVE THE MYLAR TAPE BEFORE MATING CONNECTORS.  
 5 THIS IS PACKAGED IN TRAY. (70pcs/TRAY)  
 6 BLEMISH AND HIT MARK CAN BE OCCURED THROUGH OUT THE MANUFACTURING PROCESS WHICH DOESN' T AFFECT QUALITY LEVEL.  
 7 THE DIMENSIONS IN PARENTHESES ARE FOR REFERENCES.

2	COPPER ALLOY	CONTACT AREA:GOLD 0.1 μm LEAD AREA:GOLD 0.03 μm UNDER PLATING:NICKEL 1.3 μm	3	COPPER ALLOY	CONTACT AREA:GOLD 0.1 μm LEAD AREA:TIN-PLATING 1 μm UNDER PLATING:NICKEL 1.3 μm
1	POLYAMIDE	BLACK UL94V-0	4	COPPER ALLOY	CONTACT AREA:GOLD 0.1 μm LEAD AREA:TIN-PLATING 1 μm UNDER PLATING:NICKEL 1.3 μm
6	POLYIMIDE		5	POLYSTYRENE	

NO.	MATERIAL	FINISH	REMARKS	NO.	MATERIAL	FINISH	REMARKS
2	COPPER ALLOY		CONTACT AREA:GOLD 0.1 μm LEAD AREA:GOLD 0.03 μm UNDER PLATING:NICKEL 1.3 μm	3	COPPER ALLOY		CONTACT AREA:GOLD 0.1 μm LEAD AREA:TIN-PLATING 1 μm UNDER PLATING:NICKEL 1.3 μm
1	POLYAMIDE		BLACK UL94V-0	4	COPPER ALLOY		CONTACT AREA:GOLD 0.1 μm LEAD AREA:TIN-PLATING 1 μm UNDER PLATING:NICKEL 1.3 μm

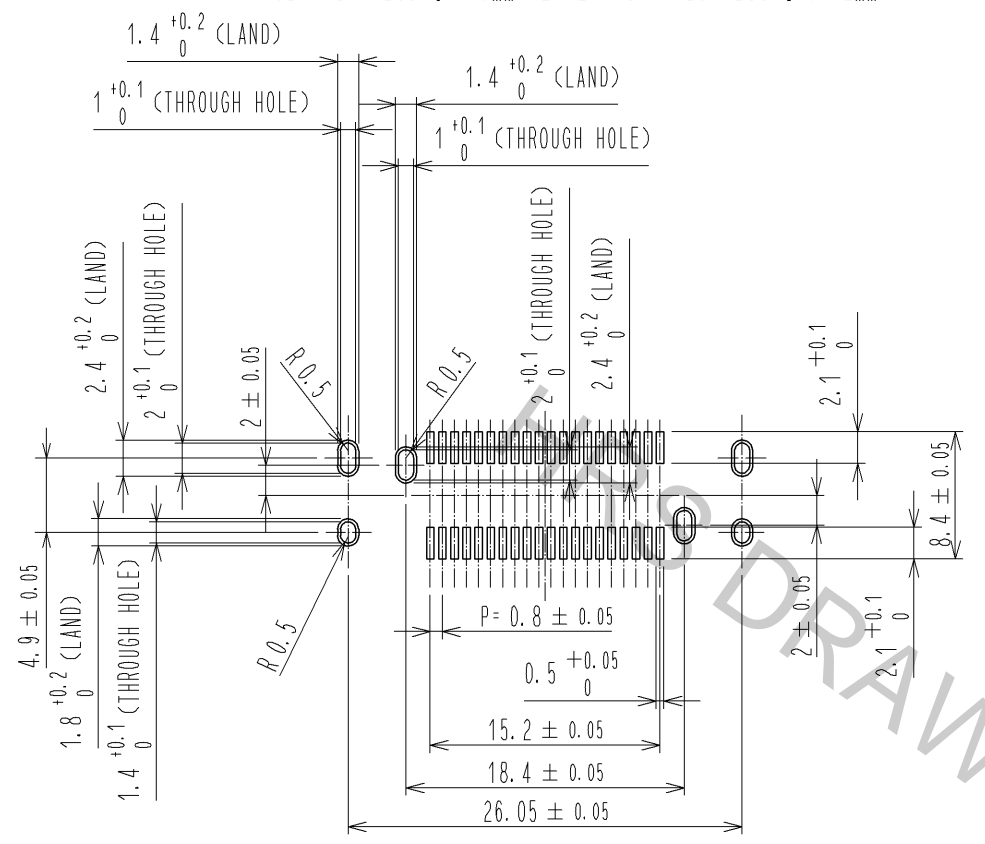
UNITS	SCALE	COUNT	DESCRIPTION OF REVISIONS	DESIGNED	CHECKED	DATE
mm	2 : 1	△	APPROVED : HS. OKAWA 14.07.16 CHECKED : HT. YAMAGUCHI 14.07.15 DESIGNED : TH. SANO 14.07.15 DRAWN : TH. SANO 14.07.15			

DRAWING NO.	EDC3-349387-00
PART NO.	FX18-40S-0.8SV10
CODE NO.	CL579-0055-1-00

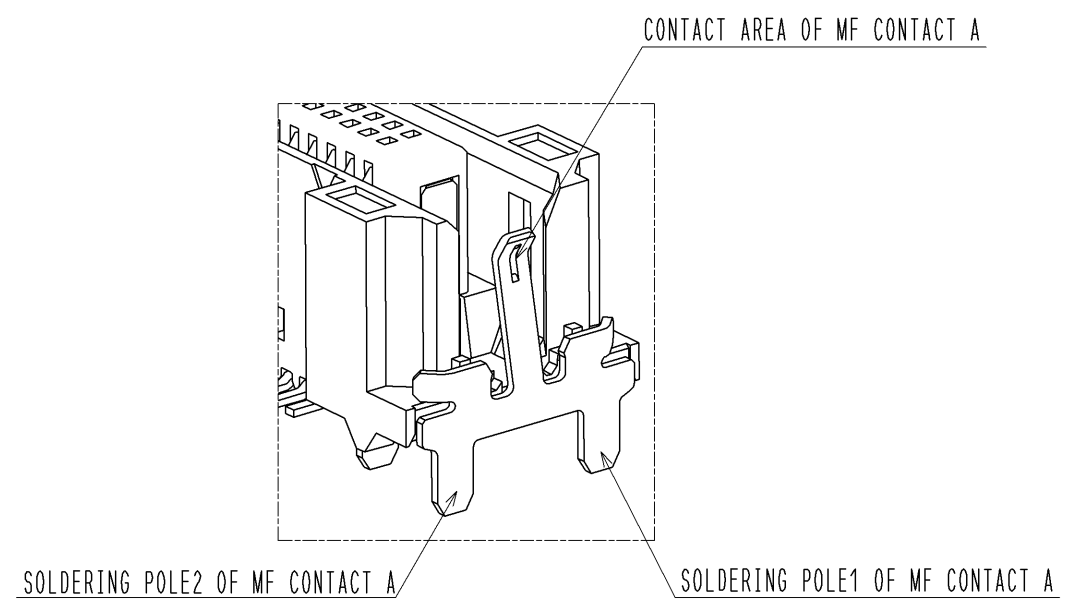
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RECOMMENDED LAND PATTERN DIMENSION OF PCB(2:1)  
(PCB THICKNESS: t=1.6mm METAL MASK THICKNESS: t=0.12mm)

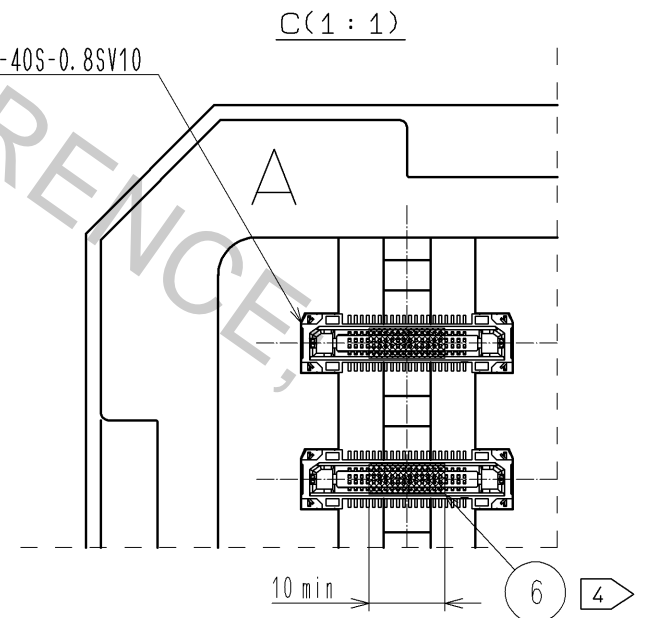
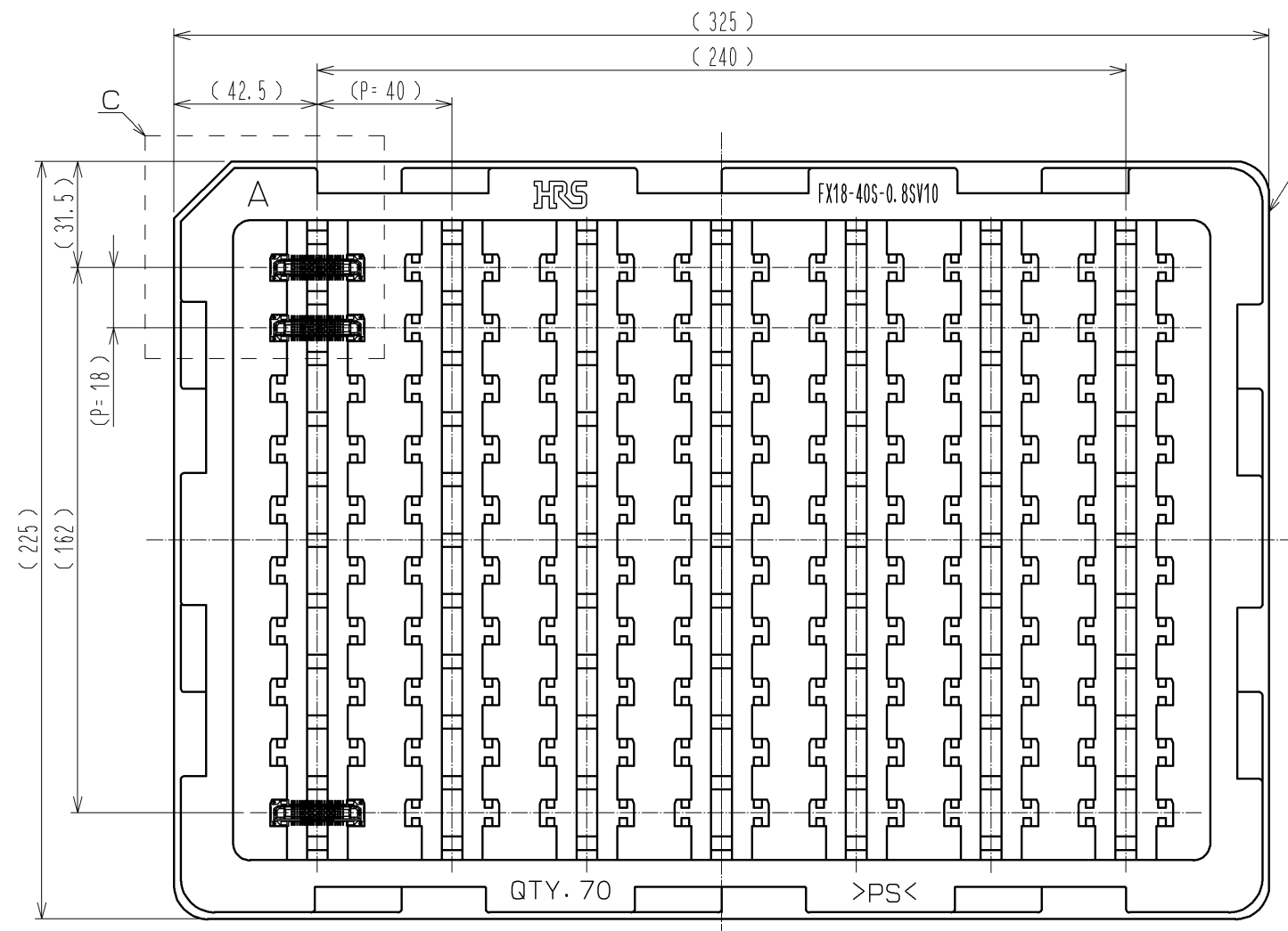


5 DRAWING FOR PACKING(1:2)

8 CONFIGURATION OF MF CONTACT A



NOTE 8 SOLDERING LEAD OF MF CONTACT A SPLITS INTO TWO POLES. BE SURE TO CONNECT TO THE SAME CIRCUIT.



<b>HRS</b>	DRAWING NO.	EDC3-349387-00	△ 2/2
	PART NO.	FX18-40S-0.8SV10	
	CODE NO.	CL579-0055-1-00	